

Layer-built substrate mfr. for high density PCB - by impregnating glass textile with polyepoxy resin varnish to facilitate the mfr. NoAbstract

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Number of Countries: 001 Number of Patents: 001

Patent Family:

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Patent Details:

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Title Terms: LAYER; BUILD; SUBSTRATE; MANUFACTURE; HIGH; DENSITY; PCB; IMPREGNATE; GLASS; TEXTILE; POLYEPOXIDE; RESIN; VARNISH; FACILITATE; MANUFACTURE; NOABSTRACT

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